PATENT ASSIGNMENT

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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Nobuyuki NEGISHI	02/05/2007
Masatoshi OYAMA	02/07/2007
Masahiro SUMIYA	01/25/2007

RECEIVING PARTY DATA

Name:	Hitachi High-Technologies Corporation	
Street Address:	24-14, Nishishinbashi, 1-chome,	
Internal Address:	Minato-ku	
City:	Tokyo	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11668057

CORRESPONDENCE DATA

Fax Number: (703)312-6666

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 7033126600

Email: ayoung@antonelli.com

Correspondent Name: Antonelli, Terry, Stout & Kraus Address Line 1: 1300 N. Seventeenth Street

Address Line 2: Suite 1800

Address Line 4: Arlington, VIRGINIA 22209

ATTORNEY DOCKET NUMBER: 500.47143X00

NAME OF SUBMITTER: William I. Solomon

Total Attachments: 1

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PATENT

REEL: 019188 FRAME: 0220

OP \$40,00 1.

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishishinbashi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S)	Date Signed
	(発明者フルネームサイン)	(署名日)
1) _	noburuki hegishi	Feb. 5. 2007
2) _	Mobuyuki NEGISHI	2/7/2007
3) _	Masatoshi OYAMA Masahiro Sumiya Masahiro SUMIYA	Jan. 25. 2007
4) _	Masaniio sumiia	
5) _		
6) _		
7) _		
8) _		
9) _		
10) _		

PATENT REEL: 019188 FRAME: 0221

RECORDED: 04/20/2007